

20	1413512	((process\$3 or cycle or defect\$4 or fail\$4 or fault\$4 or reject\$4) near3 (time or rate)) or ((semiconductor or (semi adj conductor) or semi-conductor or wafer or IC or (integrated adj circuit) or lot or (micro adj electronic) or microelectronic or memory or (logic adj unit) or microprocessor or process\$3 or fabricat\$3 or produc\$4 or manufactur\$3 or deposit\$3 or etch\$3 or metrology or measur\$3 or tool\$3) with (uniform\$3 or variability or capabilit\$4 or capacity))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/28 21:17
21	117771	((process\$3 or cycle or defect\$4 or fail\$4 or fault\$4 or reject\$4) near3 (time or rate)) or ((semiconductor or (semi adj conductor) or semi-conductor or wafer or IC or (integrated adj circuit) or lot or (micro adj electronic) or microelectronic or memory or (logic adj unit) or microprocessor or process\$3 or fabricat\$3 or produc\$4 or manufactur\$3 or deposit\$3 or etch\$3 or metrology or measur\$3 or tool\$3) near3 (uniform\$3 or variability or capabilit\$4 or capacity))) with (perform\$4 or quality or qualification or qualify\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/28 21:19
22	2902	((process\$3 or cycle or defect\$4 or fail\$4 or fault\$4 or reject\$4) near3 (time or rate)) or ((semiconductor or (semi adj conductor) or semi-conductor or wafer or IC or (integrated adj circuit) or lot or (micro adj electronic) or microelectronic or memory or (logic adj unit) or microprocessor or process\$3 or fabricat\$3 or produc\$4 or manufactur\$3 or deposit\$3 or etch\$3 or metrology or measur\$3 or tool\$3) near3 (uniform\$3 or variability or capabilit\$4 or capacity))) with (perform\$4 or quality or qualification or qualify\$3) same chamber	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/28 21:19
23	73	((process\$3 or cycle or defect\$4 or fail\$4 or fault\$4 or reject\$4) near3 (time or rate)) or ((semiconductor or (semi adj conductor) or semi-conductor or wafer or IC or (integrated adj circuit) or lot or (micro adj electronic) or microelectronic or memory or (logic adj unit) or microprocessor or process\$3 or fabricat\$3 or produc\$4 or manufactur\$3 or deposit\$3 or etch\$3 or metrology or measur\$3 or tool\$3) near3 (uniform\$3 or variability or capabilit\$4 or capacity))).clm. with ((perform\$4 or quality or qualification or qualify\$3) with chamber)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/28 21:59
24	14	((qualification or qualify\$3) with chamber).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/28 22:01
25	63	((qualification or qualify\$3) with (tool or equipment or fab or etch\$3 or deposit\$7 or implant\$7 or planariz\$8 or polish\$5)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/28 22:04
26	10	((qualification or qualify\$3) with (tool or equipment or fab or etch\$3 or deposit\$7 or implant\$7 or planariz\$8 or polish\$5).clm.) and (chamber with (tool or equipment or fab or etch\$3 or deposit\$7 or implant\$7 or planariz\$8 or polish\$5))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/28 22:05
27	2168	((qualification or qualif\$5 or qual) with (tool or equipment or fab or etch\$3 or deposit\$7 or implant\$7 or planariz\$8 or polish\$5 or chamber))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/28 22:05
28	894	((qualification or qualif\$5 or qual) near3 (tool or equipment or fab or etch\$3 or deposit\$7 or implant\$7 or planariz\$8 or polish\$5 or chamber))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/28 22:05
29	160	((qualification or qualif\$5 or qual) near3 (tool or equipment or fab or etch\$3 or deposit\$7 or implant\$7 or planariz\$8 or polish\$5 or chamber)) and (chamber with (tool or equipment or fab or etch\$3 or deposit\$7 or implant\$7 or planariz\$8 or polish\$5))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/28 22:06

30	44	(((((qualification or qualif\$5 or qual) near3 (tool or equipment or fab or etch\$3 or deposit\$7 or implant\$7 or planariz\$8 or polish\$5 or chamber))) and (chamber with (tool or equipment or fab or etch\$3 or deposit\$7 or implant\$7 or planariz\$8 or polish\$5))) and (118/719.ccls. or 29/25.01.ccls. or 427/9.ccls. or 438/5-18.ccls. or 700/19,49,52,99-104,108-111,119-121,123.ccls.))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/28 22:06
----	----	--	---	------------------